

OXFORD LASERS A SERIES

Cutting with built-in programs

Starting Procedure

1. Turn on the machine by key (*Power ON/OFF*) clockwise to position I.
2. Wait till the PC and MS Windows start up.
3. Check main instrument door (green with orange window) are closed.
4. Run *Cimita* program (on Desktop) as an Operator (without password)
5. Laser Dicer is ready to cut after approx. 5–10 minutes. Keep an eye on status field on the top right part of the monitor (Laser status) – *Running ready* is what you are waiting for.

Cutting/Scribing

6. Move to *Programs* in *Cimita* software and start the *Enable + home all axes* program (all 4 axes must be green).
7. Press the *Shutter Close* button and open the door.
8. Place your sample/sheet foil/wafer/etc. onto the table and clamp at your convenience – for example silicon wafers do not have to be clamped.
9. Close the door.
10. By using controls on the screen (top left) find the starting point of your cut and focus camera on the surface (*Z-distance* is usually around 55 mm).
11. Set the *Laser Frequency* adequately to your material.
12. Find a program on the screen which fits your needs (Cut line, Cut Rectangle, Cut Target, ...).
13. Start the program and follow the instructions – press the button *Open Shutter*, set the cutting speed, power and number of passes.
14. When the program is finished, you can check the sample by starting the program *Jig Load/Unload*. Wait till the chuck move to the front, press *Close Shutter* button, open the door and check your sample.
15. In case you want to cut again, close the door, press *Ok* on the screen and repeat this procedure from point 11.

Shutting up Procedure

16. Save all your work (optional) and close all programs – close *Cimita* by cross on the top right corner of the window.
17. First turn off PC from start menu. When the screen gets black, turn off the machine by key (*Power ON/OFF*).